

IN THE CLAIMS:

Please amend claims 56, 64, and 65, and add new claims 75-80, as shown in the complete list of claims that is presented below:

Claims 1-55 (cancelled).

56. (currently amended) A semiconductor device comprising:

a semiconductor chip having a plurality of electrode pads;

a molding resin structure covering the semiconductor chip, the molding resin structure having a first main surface and a second main surface opposite to the first main surface;

a plurality of terminals formed on the first main surface of the structure, the terminals being electrically connected to the electrode pads, respectively; and

a ~~stripy~~ stripe groove formed on the second main surface of the structure, wherein the stripe groove divides the second main surface asymmetrically.

57. (previously presented) A semiconductor device according to claim 56, wherein the stripe groove has a V shaped profile.

58. (previously presented) A semiconductor device according to claim 56, wherein the stripe groove has a U shaped profile.

59. (previously presented) A semiconductor device according to claim 56, further comprising an auxiliary stripe groove formed on the second main surface of the structure, wherein the stripe groove and the auxiliary stripe groove intersect at an off-center point.

60. (previously presented) A semiconductor device according to claim 56, further comprising an auxiliary stripe groove formed on the second main surface of the structure, wherein the auxiliary stripe groove is parallel to the stripe groove, and wherein the auxiliary stripe groove divides the second main surface asymmetrically.

61. (previously presented) A semiconductor device according to claim 56, wherein the terminals are arranged in a plurality of rows.

62. (previously presented) A semiconductor device according to claim 61, wherein the stripe groove is formed at a position corresponding to one of the rows of the terminals.

63. (previously presented) A semiconductor device comprising:  
a semiconductor chip having a plurality of electrode pads;  
a molding resin structure covering the semiconductor chip, the molding resin structure having a first main surface and a second main surface opposite to the first main surface, the second main surface having four sides;  
a plurality of terminals formed on the first main surface of the structure, the terminals being electrically connected to the electrode pads, respectively; and  
a steplike section formed on one of the sides of the second main surface of the structure.

64. (currently amended) A semiconductor device according to ~~to~~ to claim 63, wherein a thickness of the structure at the steplike section becomes smaller approaching the one of the edges.

65. (currently amended) A semiconductor device according to claim 63, further comprising an auxiliary steplike section formed on ~~the other~~ another one of the sides of the second main surface of the structure, wherein the auxiliary steplike section and the steplike section intersect at a corner of the main surface.

66. (previously presented) A semiconductor device according to claim 63, wherein the terminals are arranged in a plurality of rows.

67. (previously presented) A semiconductor device comprising:

a semiconductor chip having a plurality of electrode pads;

a sealing resin structure covering the semiconductor chip, the sealing resin structure having a first main surface and a second main surface opposite to the first main surface, the second main surface having a first roughness;

a plurality of terminals formed on the first main surface of the structure, the terminals being electrically connected to the electrode pads, respectively; and

a stripe portion formed on the second main surface of the structure, the stripe portion having a second roughness that is coarser than the first roughness, wherein the stripe portion divides the second main surface asymmetrically.

68. (previously presented) A semiconductor device according to claim 67, wherein the stripe portion has a groove.

69. (previously presented) A semiconductor device according to claim 68, wherein the groove has a V shaped profile.

70. (previously presented) A semiconductor device according to claim 68, wherein the groove has a U shaped profile.

71. (previously presented) A semiconductor device according to claim 67, further comprising an auxiliary stripe portion formed on the second main surface of the structure, the auxiliary strip portion substantially having the second roughness, wherein the stripe portion and the auxiliary stripe portion intersect at an off-center point.

72. (previously presented) A semiconductor device according to claim 67, further comprising an auxiliary stripe portion formed on the second main surface of the structure in parallel with the strip portion, the auxiliary strip portion substantially having the second roughness, wherein the auxiliary stripe portion divides the second main surface asymmetrically.

73. (previously presented) A semiconductor device according to claim 67, wherein the terminals are arranged in a plurality of rows.

74. (previously presented) A semiconductor device according to claim 73, wherein the stripe portion is formed at a position corresponding to one of the rows of the terminals.

75. (new) A semiconductor device according to claim 56, wherein the stripe groove has a function of indicia for recognizing an orientation of the semiconductor device.

76. (new) A semiconductor device according to claim 63, wherein the steplike section has a function of indicia for recognizing an orientation of the semiconductor device.

77. (new) A semiconductor device according to claim 67, wherein the stripe portion has a function of indicia for recognizing an orientation of the semiconductor device.

78. (new) A semiconductor device according to claim 56, wherein the stripe groove is formed over the semiconductor chip.

79. (new) A semiconductor device according to claim 67, wherein the stripe portion is formed over the semiconductor chip.

80. (new) A semiconductor device according to claim 63, wherein at least one of the sides of the second main surface of the structure lacks a steplike section.